Panasonic

MA4X862 (MA862)

Silicon epitaxial planar type

For band switching

■ Features

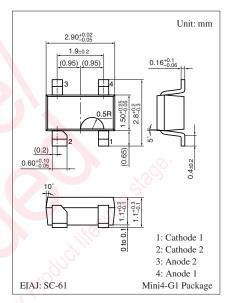
- Two electrically independent elements incorporated
- Small diode capacitance C_D
- Low forward dynamic resistance r_f
- Optimum for a band switching of tuner

■ Absolute Maximum Ratings T_a = 25°C

Parameter		Symbol	Rating	Unit	
Reverse voltage		V _R	35	V	
Forward current	Single	I_{F}	100	mA	
	Double *1		75		
Operating ambient temperature *2		T _{opr}	-25 to +85	°C	
Storage temperature		T_{stg}	-55 to +100	°C	

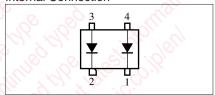
Note) *1: Value of each diode in double diodes used.

*2: Maximum ambient temperature during operation.



Marking Symbol: M1I

Internal Connection



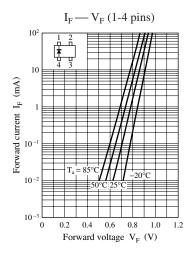
■ Electrical Characteristics T_a = 25°C ± 3°C

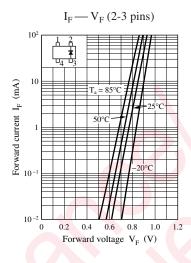
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 100 \text{ mA}$	7.60		1.0	V
Reverse current	I_R	V _R = 33 V			100	nA
Diode capacitance	C_{D}	$V_R = 6 \text{ V}, f = 1 \text{ MHz}$			1.2	pF
Forward dynamic resistance	r _{f1} *1	$I_F = 2 \text{ mA}, f = 100 \text{ MHz}$			0.65	Ω
	r _{f2} *2	isil and			0.98	

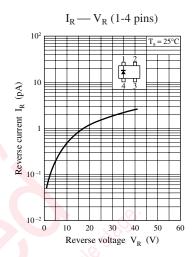
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

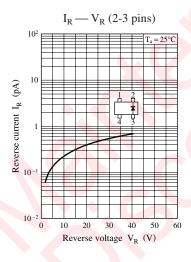
- 2. Absolute frequency of input and output is 100 MHz.
- 3. *1: Measuring instrument; Nihon Koshuha MODEL TDC-121A
 - *2: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

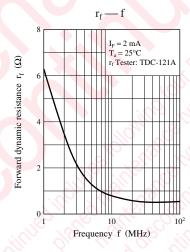
Note) The part number in the parenthesis shows conventional part number.

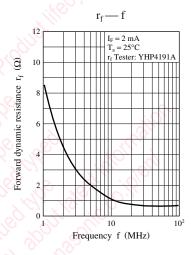


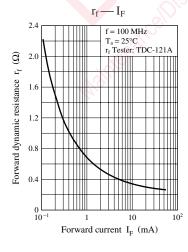


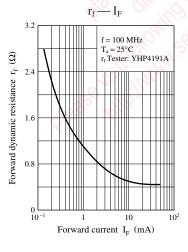


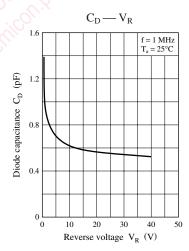




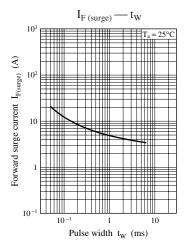








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